## TOSHIBA

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSII)

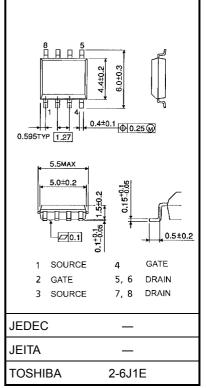
# **TPC8206**

Lithium Ion Battery Applications Notebook PC Applications Portable Equipment Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance:  $R_{DS}$  (ON) = 40 m $\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 7.0 \text{ S}$  (typ.)
- Low leakage current:  $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 60 \ V)$
- Enhancement-mode:  $V_{th}$  = 1.3 to 2.5 V (VDS = 10 V, ID = 1 mA)

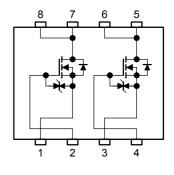
#### Maximum Ratings (Ta = 25°C)

Cha	racteristics	Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	60	V	
Drain-gate volta	ge (R <sub>GS</sub> = 20 kΩ)	V <sub>DGR</sub>	60	V	
Gate-source vol	tage	V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	ID	5	Α	
	Pulse (Note 1)	I <sub>DP</sub>	20	~	
Drain power dissipation	Single-device operation (Note 3a)	P <sub>D (1)</sub>	1.5		
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	1.0	W	
Drain power dissipation	Single-device operation (Note 3a)	P <sub>D (1)</sub>	0.75		
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	0.45	W	
Single pulse avalanche energy (Note 4)		E <sub>AS</sub>	92	mJ	
Avalanche curre	nt	I <sub>AR</sub>	5	А	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E <sub>AR</sub>	0.1	mJ	
Channel temper	ature	T <sub>ch</sub>	150	°C	
Storage tempera	ature range	T <sub>stg</sub>	-55 to 150	°C	



Weight: 0.080 g (typ.)

#### **Circuit Configuration**



Note: For (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5), please refer to the next page.

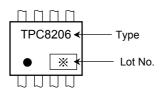
This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit		
The median statement of a median	Single-device operation (Note 3a)	R <sub>th (ch-a)</sub> (1)	83.3	°C/W	
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	125		
Thermal resistance, channel to embient	Single-device operation (Note 3a)	R <sub>th (ch-a)</sub> (1)	167		
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	278	°C/W	

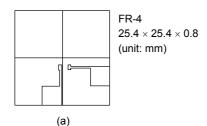
#### Marking (Note 6)

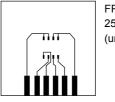


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

a) Device mounted on a glass-epoxy board (a)





b) Device mounted on a glass-epoxy board (b)

FR-4 25.4 × 25.4 × 0.8 (unit: mm)



Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device. (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device. (During dual operation, power is evenly applied to both devices.)

Note 4:  $V_{DD} = 25 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 5.0 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = 5 A

- Note 5: Repetitive rating; pulse width limited by maximum channel temperature
- Note 6: on lower left of the marking indicates Pin 1.



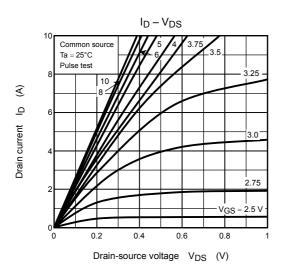
Electrical Characteristics (Ta = 25°C)

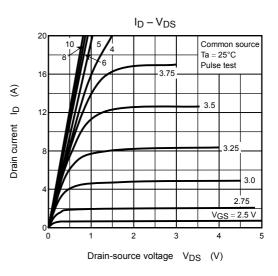
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rrent	I <sub>GSS</sub>	$V_{GS}=\pm 16~V,~V_{DS}=0~V$	_	_	±10	μA
Drain cut-OFF cu	ırrent	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	— — 10		10	μA
Drain-source breakdown voltage		V (BR) DSS	$I_{D} = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	60	_	_	V
		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -12 \text{ V}$	35	_	_	v
Gate threshold ve	oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	1.3	_	2.5	V
Drain-source ON resistance		Den server	$V_{GS} = 4 V, I_D = 2.5 A$	_	55	75	mΩ
		R <sub>DS (ON)</sub>	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 2.5 \text{ A}$	_	40	50	
Forward transfer admittance		Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 2.5 \text{ A}$	3.5	7.0	_	S
Input capacitance		C <sub>iss</sub>	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$	_	800	_	pF
Reverse transfer capacitance		C <sub>rss</sub>		_	60	_	
Output capacitance		C <sub>oss</sub>		_	190	_	
	Rise time	tr	$V_{GS} \stackrel{10}{}_{0}V \qquad I_{D} = 2.5 \text{ A}$	_	2.6	_	- ns
	Turn-ON time	t <sub>on</sub>		_	10	_	
Switching time	Fall time	t <sub>f</sub>		_	2.3	_	
	Turn-OFF time	t <sub>off</sub>	$V_{DD}\simeq 30~V \label{eq:VDD}$ Duty $\leq$ 1%, $t_w=10~\mu s$	_	22	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq 48$ V, $V_{GS} = 10$ V, $I_D = 5$ A		17	_	nC
Gate-source charge		Q <sub>gs</sub>			12	—	
Gate-drain ("miller") charge		Q <sub>gd</sub>			5	_	

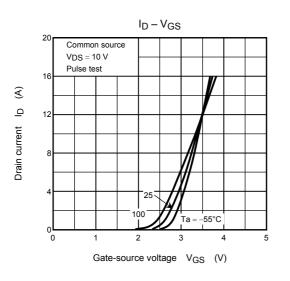
### Source-Drain Ratings and Characteristics ( $Ta = 25^{\circ}C$ )

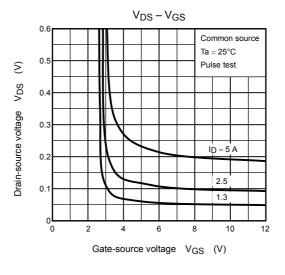
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	20	А
Forward voltage (diode)		V <sub>DSF</sub>	$I_{DR} = 5 \text{ A}, \text{ V}_{GS} = 0 \text{ V}$	_	_	-1.2	V

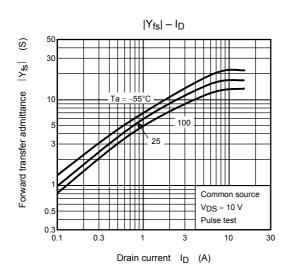
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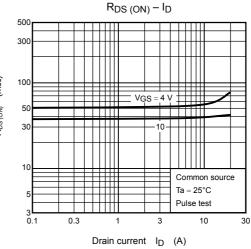




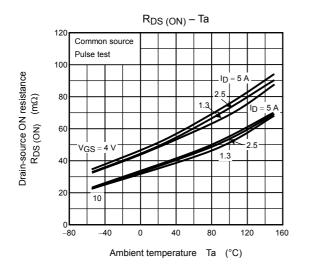


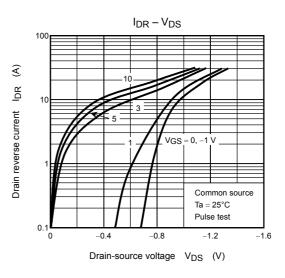


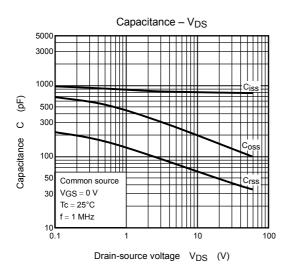
Drain-source ON resistance R<sub>DS (ON)</sub> (mΩ) t

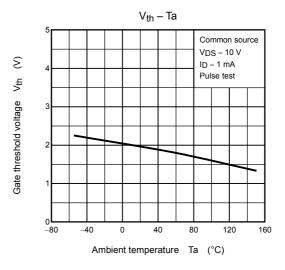


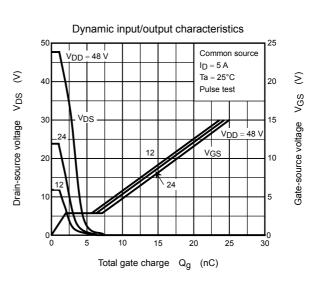
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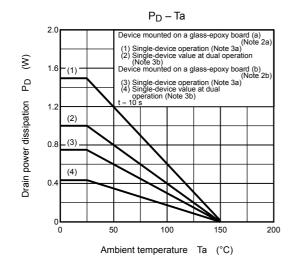


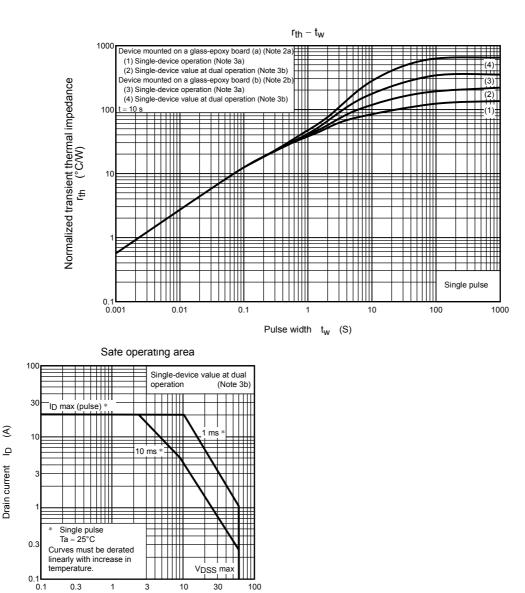












Drain-source voltage  $V_{DS}$ 

(V)

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